

10997 U.S. PTO

10/055266

01/22/02

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10055266	01/22/2002	257	138	2811	Q. Vu

**APPLICANTS: Choi Ki-won;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

REPUBLIC OF KOREA 2001-5945 02/07/2001

PG-PUB DO NOT PUBLISH ☐RESCIND ☐

Foreign priority claimed

☐ yes ☐ no

35 USC 119 conditions met

☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO.

9898-208

TITLE : Semiconductor package having changed substrate design using special wire bonding

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner			
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawg.	Figs Drawg.
		Print Fig.	
Primary Examiner		Application Examiner	
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